

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV:	: Not In VersionControl
LAYER NAME = Top Overlay				
PLOT NAME = Top Overlay	GENERATED : 1/19/2	015 2:15:31	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV:	: Not In VersionControl
LAYER NAME = Top Solder				
PLOT NAME = Top Solder Mask	GENERATED : 1/19/2	015 2:15:32	PM	TEXAS INSTRUMENTS

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ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV:	: Not In VersionControl
LAYER NAME = Top Layer				
PLOT NAME = Top Layer	GENERATED : 1/19/2	2:15:33	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV	: Not In VersionControl
LAYER NAME =				
PLOT NAME = MidLayer1	GENERATED : 1/19/2	2:15:33	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV	: Not In VersionControl
LAYER NAME =				
PLOT NAME = MidLayer2	GENERATED : 1/19/2	2:15:34	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV:	Not In VersionControl
LAYER NAME = Bottom Layer				
PLOT NAME = Bottom Layer	GENERATED : 1/19/2	2:15:35	PM	TEXAS INSTRUMENTS



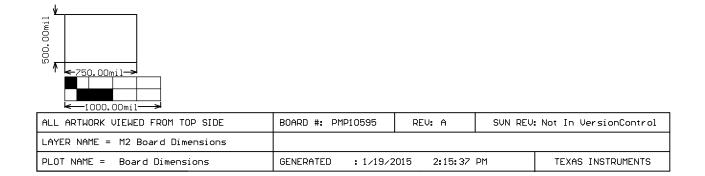
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV	: Not In VersionControl
LAYER NAME = Bottom Solder				
PLOT NAME = Bottom Solder Mask	GENERATED : 1/19/2	015 2:15:35	PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV:	: Not In VersionControl
LAYER NAME = Bottom Overlay				
PLOT NAME = Bottom Overlay	GENERATED : 1/19/2	015 2:15:36	PM	TEXAS INSTRUMENTS

			Symbol	Quantity	Finished Hole Size	Plated	Hole Type
~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~			$\bigtriangledown$	11	10.00mil (0.254mm)	РТН	Round
°°°°	v			3	39.37mil (1.000mm)	РТН	Round
				14 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP10595	REV: A	SVN REV:	: Not In VersionControl
LAYER NAME = Drill Drawing				
PLOT NAME = Drill Drawing	GENERATED : 1/19/2	2:15:36	PM	TEXAS INSTRUMENTS



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